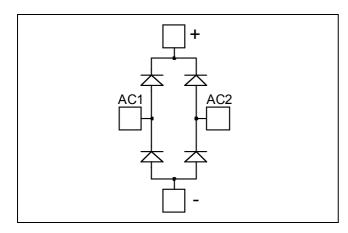


## Diode Full Bridge Power Module

$$V_{RRM} = 600V$$
  
 $I_{C} = 200A @ Tc = 80°C$ 



### **Application**

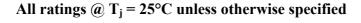
- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

#### **Features**

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration



- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant



#### **Absolute maximum ratings**

Symbol	Parameter				Max ratings	Unit	
$V_R$	Maximum DC reverse Voltage					· ·	
$V_{RRM}$	Maximum Peak Repetitive Revers	e Voltage			600	V	
$I_{F(AV)}$	Maximum Average Forward	D 41.	500/	$T_C = 25$ °C	270	A	
	Current	Duty cycle	= 50%	$T_C = 80$ °C	200		
I <sub>F(RMS)</sub>	RMS Forward Current	Duty cycle = 50%		$T_C = 45$ °C	270	А	
$I_{FSM}$	Non-Repetitive Forward Surge Cu	rrent	8.3ms	$T_C = 45^{\circ}C$	1500		

TAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

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**Electrical Characteristics** 

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$V_{\mathrm{F}}$	Diode Forward Voltage	$I_F = 200A$			1.6	2.0	
		$I_F = 400A$			2.0		V
		$I_F = 200A$	$T_{j} = 125^{\circ}C$		1.3		
$I_{RM}$	Maximum Reverse Leakage Current	$V_{\rm p} = 600 {\rm V}$	$T_i = 25^{\circ}C$			350	4
			$T_j = 125$ °C			600	μΑ
$C_{T}$	Junction Capacitance	$V_R = 600V$			380	_	pF

**Dynamic Characteristics** 

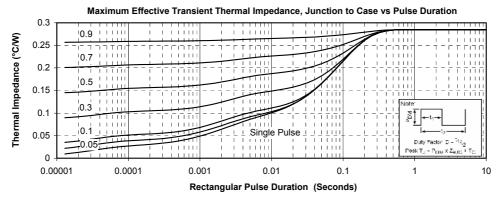
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$t_{rr}$	Reverse Recovery Time	$I_F=1A, V_R=30V$ $di/dt = 200A/\mu s$	$T_j = 25^{\circ}C$		34		ns
t	t <sub>rr</sub> Reverse Recovery Time		$T_j = 25^{\circ}C$		160		ns
ι <sub>rr</sub>			$T_j = 125$ °C		220		
Q <sub>rr</sub>	Reverse Recovery Charge	$I_F = 200A$ $V_R = 400V$	$T_j = 25^{\circ}C$		580		nC
Qrr	Reverse Recovery Charge	$di/dt = 400 \text{ A/} \mu \text{s}$	$T_j = 125$ °C		3060		пс
Inne	Reverse Recovery Current	,	$T_j = 25$ °C		10		A
$I_{RRM}$	Reverse Recovery Current		$T_{j} = 125^{\circ}C$		26		Λ
$t_{rr}$	Reverse Recovery Time	$\begin{split} I_F &= 200 A \\ V_R &= 400 V \\ di/dt &= 2000 A/\mu s \end{split}$			100		ns
Qrr	Reverse Recovery Charge		$T_j = 125$ °C		5.78		μС
$I_{RRM}$	Reverse Recovery Current				88		A

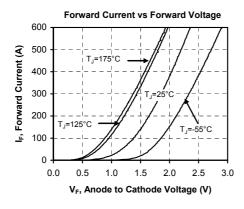
Thermal and package characteristics

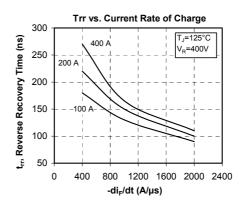
Symbol	Characteristic			Min	Typ	Max	Unit
$R_{thJC}$	Junction to Case Thermal Resistance					0.285	°C/W
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
$T_{J}$	Operating junction temperature range			-40		175	°C
$T_{STG}$	Storage Temperature Range			-40		125	
$T_{\rm C}$	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
	Wiodinting torque	For terminals	M5	2		3.5	19.111
Wt	Package Weight					300	g

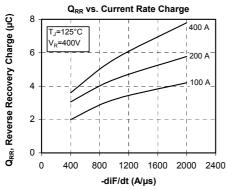


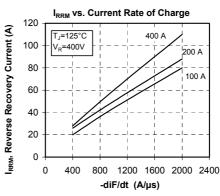
### **Typical Performance Curve**

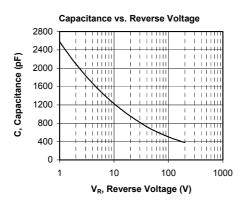


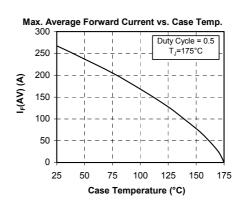






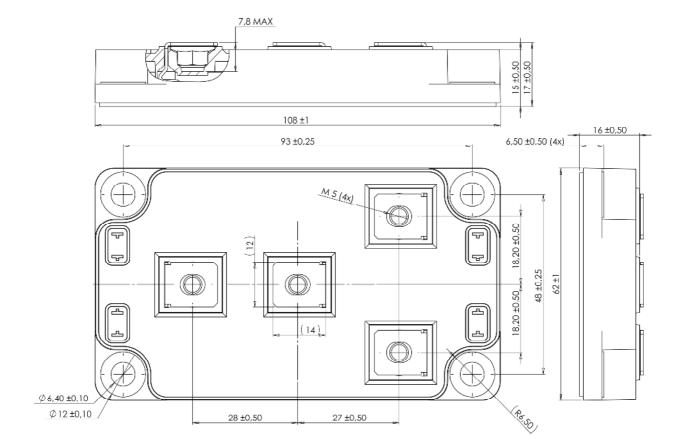








### SP6 Package outline (dimensions in mm)





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